



達鉅電子股份有限公司
REGO ELECTRONICS INC.

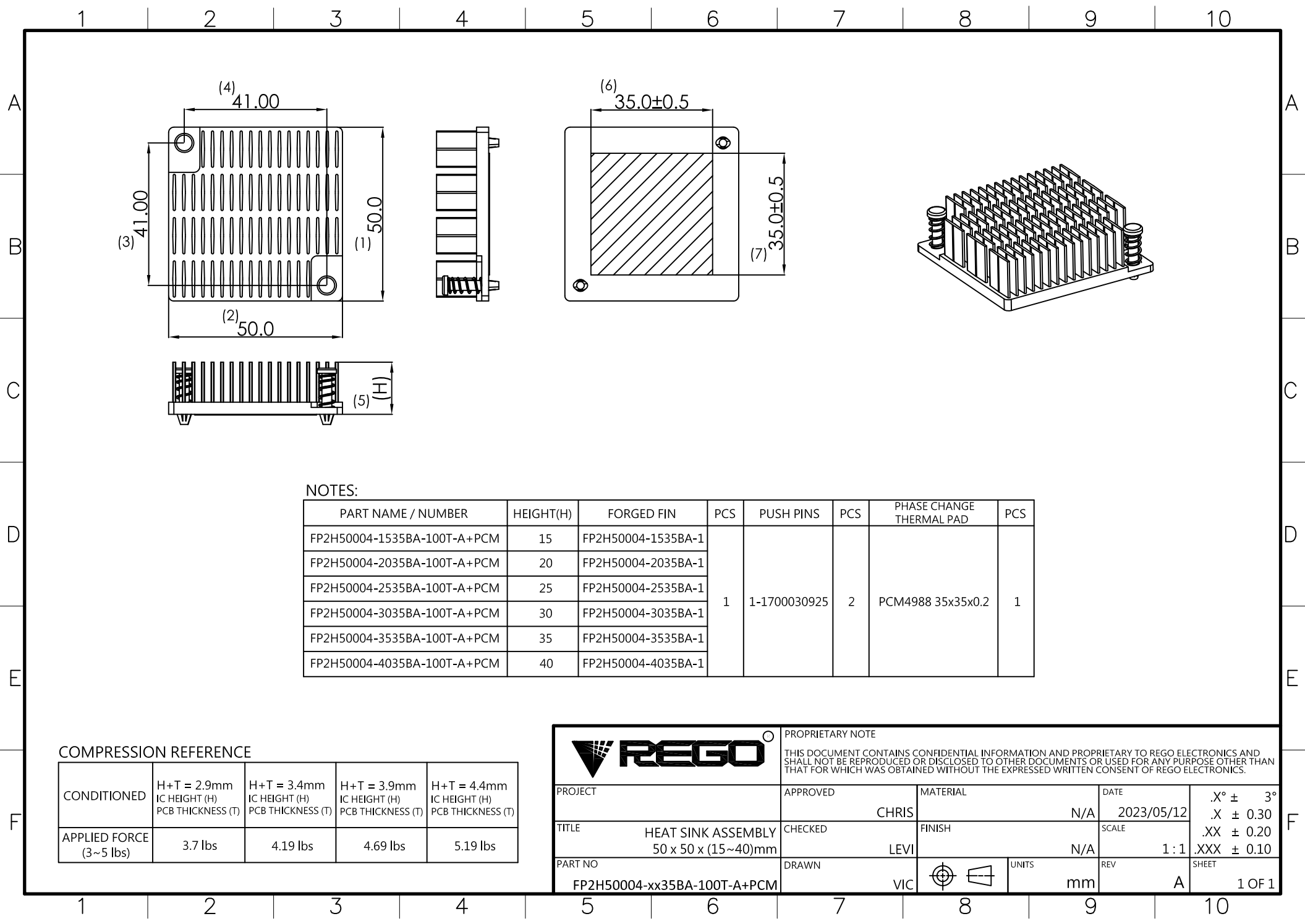
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APPROVAL SHEET

BRAND	REGO
PART NUMBER	FP2H50004-xx35BA-100T-A+PCM
DESCRIPTION	HEAT SINK ASSEMBLY 50 x 50 x (15~40)mm
CUSTOMER	
CUSTOMER P/N	

AUTHORIZED SIGNATURES

NAME			
DATE			



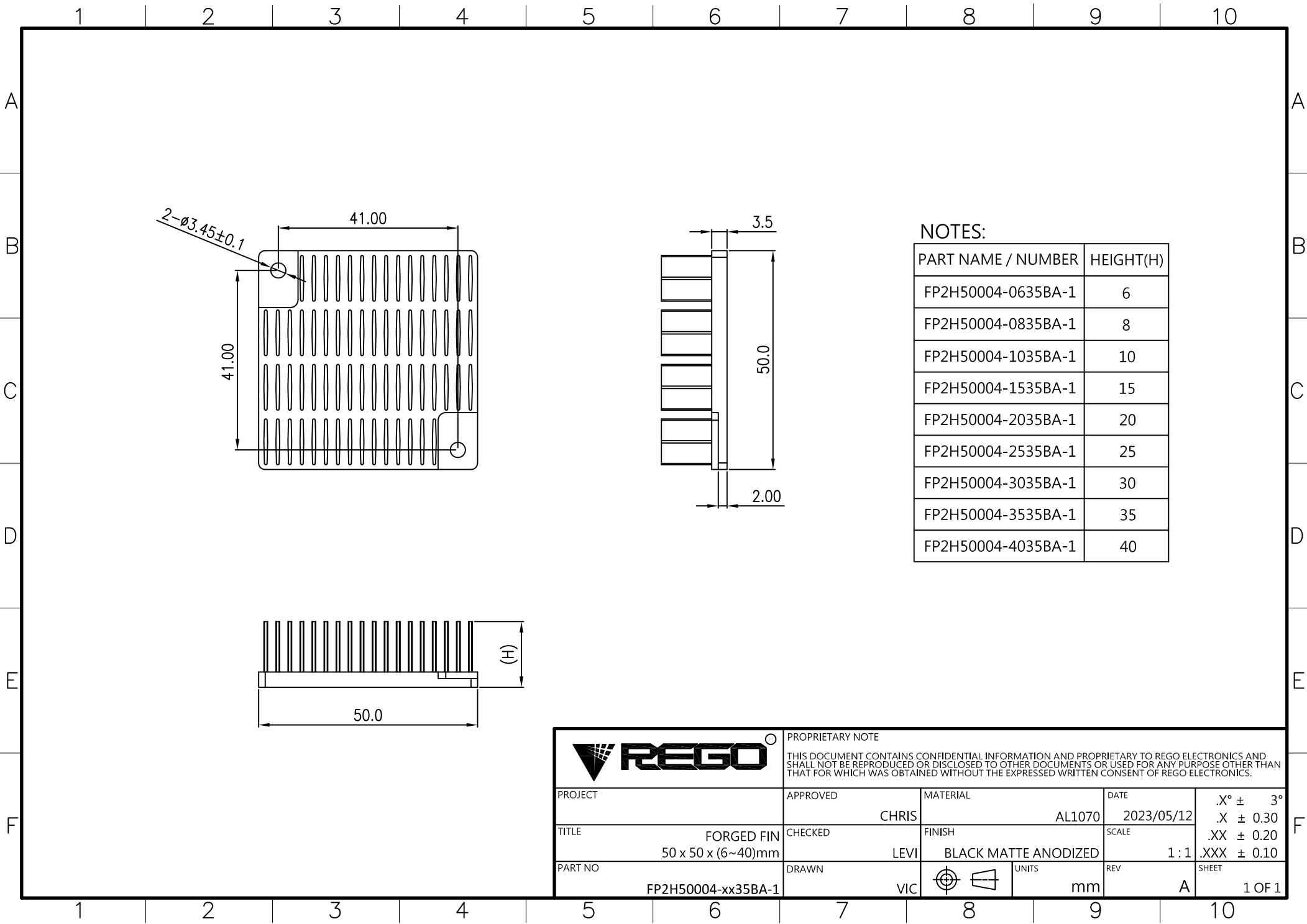
NOTES:

PART NAME / NUMBER	HEIGHT(H)	FORGED FIN	PCS	PUSH PINS	PCS	PHASE CHANGE THERMAL PAD	PCS
FP2H50004-1535BA-100T-A+PCM	15	FP2H50004-1535BA-1	1	1-1700030925	2	PCM4988 35x35x0.2	1
FP2H50004-2035BA-100T-A+PCM	20	FP2H50004-2035BA-1					
FP2H50004-2535BA-100T-A+PCM	25	FP2H50004-2535BA-1					
FP2H50004-3035BA-100T-A+PCM	30	FP2H50004-3035BA-1					
FP2H50004-3535BA-100T-A+PCM	35	FP2H50004-3535BA-1					
FP2H50004-4035BA-100T-A+PCM	40	FP2H50004-4035BA-1					

COMPRESSION REFERENCE

CONDITIONED	H+T = 2.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.4mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 4.4mm IC HEIGHT (H) PCB THICKNESS (T)
APPLIED FORCE (3~5 lbs)	3.7 lbs	4.19 lbs	4.69 lbs	5.19 lbs

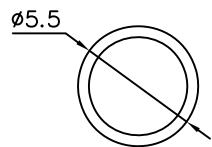
		PROPRIETARY NOTE THIS DOCUMENT CONTAINS CONFIDENTIAL INFORMATION AND PROPRIETARY TO REGO ELECTRONICS AND SHALL NOT BE REPRODUCED OR DISCLOSED TO OTHER DOCUMENTS OR USED FOR ANY PURPOSE OTHER THAN THAT FOR WHICH WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF REGO ELECTRONICS.			
PROJECT	APPROVED	MATERIAL	DATE		
	CHRIS	N/A	2023/05/12	.X° ± 3°	
TITLE	CHECKED	FINISH	SCALE		
HEAT SINK ASSEMBLY 50 x 50 x (15~40)mm	LEVI	N/A	1 : 1	.XX ± 0.20	
PART NO	DRAWN	UNITS	REV	SHEET	
FP2H50004-xx35BA-100T-A+PCM	VIC	mm	A	1 OF 1	



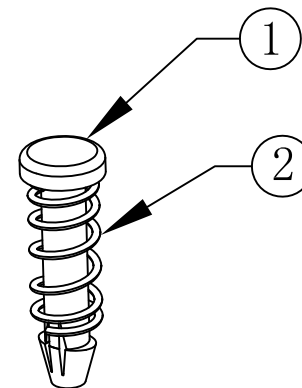
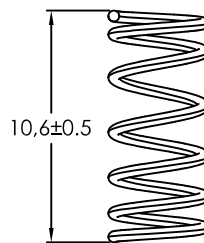
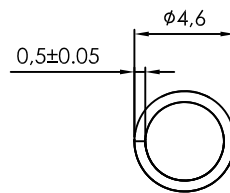
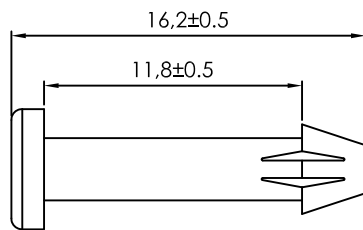
NOTES:

PART NAME / NUMBER	HEIGHT(H)
FP2H50004-0635BA-1	6
FP2H50004-0835BA-1	8
FP2H50004-1035BA-1	10
FP2H50004-1535BA-1	15
FP2H50004-2035BA-1	20
FP2H50004-2535BA-1	25
FP2H50004-3035BA-1	30
FP2H50004-3535BA-1	35
FP2H50004-4035BA-1	40

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PROJECT	APPROVED	MATERIAL	DATE	.X° ± 3° .X ± 0.30 .XX ± 0.20 .XXX ± 0.10	
TITLE	CHECKED	FINISH	SCALE		
PART NO	DRAWN	UNITS	REV		
FORGED FIN 50 x 50 x (6~40)mm		CHRIS LEVI VIC	AL1070 BLACK MATTE ANODIZED mm	2023/05/12 1:1 A	SHEET 1 OF 1

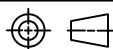


HOLE IN PCB $\phi 3.1 \pm 0.05$



ITEM	DESCRIPTION	MATERIAL	FINISH
1	BODY	NYLON 66	WHITE
2	SPRING	PIANO WIRE	NICKEL

ITEM	NUMERICAL VALUE
SPRING DIAMETER D=	4.1 mm
WIRE DIAMETER d=	0.5 mm
TOTAL COIL Q'TY Na=	6
FREE LENGTH L0=	10.6 mm
SPRING COEFFICIENT K=	226.71 g/mm

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		PROJECT	APPROVED	MATERIAL	DATE
			CHRIS	SEE NOTE	2020/10/20
TITLE		CHECKED	LEVI	FINISH	SCALE
PUSH PIN				SEE NOTE	1:1
PART NO		DRAWN	VIC	UNITS	REV
1-1700030925				mm	A
				SHEET	
				1 OF 1	

PCM4988

High Thermal Conductivity Phase Change Material

Honeywell's PCM4988, a highly thermally conductive Phase Change Material (PCM) in pad format, was designed to minimize thermal resistance at interfaces. Based on a novel polymer PCM system, this material exhibits excellent wetting at interfaces during typical operating temperature range, resulting in very low surface contact resistance.

A proprietary filler material provides high thermal conductivity (2.0–5.0 W/m°C) and a low thermal impedance ($<0.20^{\circ}\text{C cm}^2/\text{W}$), suitable for high performance IC devices.

PCM4988 in Convenient Pad Format



*Stencil printable material is available as PCM4988-SP

Honeywell TIMs Serve Multiple Applications



Automotive & Power



IT/Enterprise



Telecommunications



Consumer Electronics



FEATURES & BENEFITS

- High performance filler and polymer technology
- Phase change at 45°C
- Highly conductive filler loading to optimize performance
- Superior handling and reworkability
- Superior reliable thermal performance
- Excellent thermal capability to fit different needs

PCM4988 Technical Information

Physical Properties	Unit	Test Method	PCM4988
Thermal Conductivity	W/m·K	ASTM D5470	2.0
Thermal Impedance @ no shim (Typical Value)	°C -cm ² /W	ASTM D5470 Modified	0.14
Specific Gravity		ASTM D374	2.2
Viscosity (Typical Value)	Pa·s @2 1/s, 25°C	RehometerHON	NA
Volume Resistivity	Ω·cm	ASTM D257-700	8.2x10 ¹⁴
Thickness Range	mm		0.20-1.00

STORAGE CONDITION

Refer to product label.

THERMAL IMPEDANCE POST RELIABILITY

(No shim @ 40psi)

End of Line 0.14 °C-cm²/W

Temperature Cycle "B" 0.10 °C-cm²/W

(-55°C to +125°C , 1000 cycles)

Product Use

Clamping pressure and temperature are suggested to achieve a minimum bond line thickness of the thermal interface material, typically less than 1.5 mil (0.038mm) for best thermal performance.

More Honeywell TIMs

PCM4988 is part of Honeywell's TIM Solutions family of phase change materials. Whatever the thermal challenge, we offer a TIM product that provides just the right characteristics for your application. Find out more about:

PTM7000 Series PTM6000 Series
PTM5000 Series PCM45F Series
Hybrid Series LTM Series By

visiting: electronicmaterials.com



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OUR COMMITMENT TO SUSTAINABILITY

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